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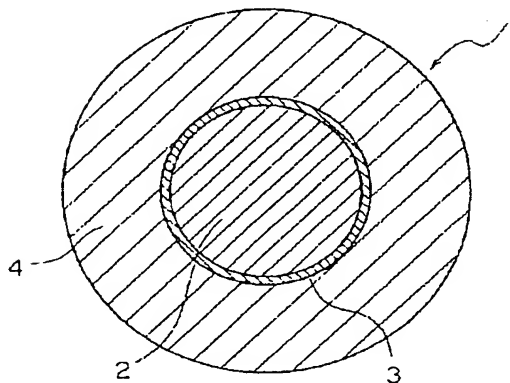
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**(54) SEMICONDUCTOR PACKAGE AND ITS  
MANUFACTURING METHOD**

**(57) Abstract:**

**PROBLEM TO BE SOLVED:** To provide a composite microball that has at least 20  $\mu\text{m}$  solder at the outer periphery of a core ball and its manufacturing method, and a semiconductor package that mounts a semiconductor device by using the composite microball.

**SOLUTION:** In the package of a semiconductor device that mounts the semiconductor device and at the same time the microball as an electric contact, the microball consists of a composite microball 1 having a conductive film around a core ball 2, the core ball has a diameter of 30 to 100  $\mu\text{m}$ , a sufficiently excellent rolling property, a superior diameter accuracy, and the conductive film has a solder plated layer 4 that is uniformly formed on an outer-periphery surface and has a thickness of 10  $\mu\text{m}$  or more, mounts the composite microball 1, and can accurately control the dimension accuracy of a Z shaft of the package.



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